P-Channel 30-V (D-S) MOSFET

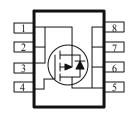
These miniature surface mount MOSFETs utilize High Cell Density process. Low r_{DS(on)} assures minimal power loss and conserves energy, making this device ideal for use in power management circuitry. Typical applications are PWMDC-DC converters, power management in portable and battery-powered products such as computers, printers, battery charger, telecommunication power system, and telephones power system.

•	Low $r_{DS(on)}$ Provides Higher Efficiency and
	Extends Battery Life

- Miniature SO-8 Surface Mount Package Saves Board Space
- High power and current handling capability
- Extended VGS range (±25) for battery pack applications

PRODUCT SUMMARY				
$V_{\mathrm{DS}}\left(\mathrm{V}\right) = r_{\mathrm{DS}\left(\mathrm{on}\right)} \mathrm{m}(\Omega) = I_{\mathrm{D}}\left(\mathrm{A}\right)$				
-30	$19 @ V_{GS} = -10V$	-9.5		
-30	$30 @ V_{GS} = -4.5V$	-7.5		





ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C UNLESS OTHERWISE NOTED)						
Parameter			Maximum	Units		
Drain-Source Voltage			-30	V		
Gate-Source Voltage			±25	V		
C t P · C t ^a	$T_A=25^{\circ}C$]] _{T_}	-9.5			
Continuous Drain Current ^a	$T_{A}=25^{\circ}C$ $T_{A}=70^{\circ}C$	1D	-8.3	A		
Pulsed Drain Current ^b		I_{DM}	±50			
Continuous Source Current (Diode Conduction) ^a		I_S	-2.1	A		
D D: a	$T_A=25^{\circ}C$	D	3.1	W		
Power Dissipation ^a	$T_{A}=25^{\circ}C$ $T_{A}=70^{\circ}C$	ГБ	2.6			
Operating Junction and Storage Temperature Range		T_{J}, T_{stg}	-55 to 150	°C		

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Maximum	Units	
Maximum Junction-to-Case ^a	t <= 5 sec	$R_{ heta JC}$	25	°C/W	
Maximum Junction-to-Ambient ^a	t <= 10 sec	$R_{\theta JA}$	50	°C/W	

1

Notes

- a. Surface Mounted on 1" x 1" FR4 Board.
- b. Pulse width limited by maximum junction temperature

D			Limits				
Parameter	Symbol	Symbol Test Conditions		Тур	Max	Unit	
Static					•		
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = -250 \text{ uA}$	-1				
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 25 \text{ V}$			±100	nA	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -24 \text{ V}, V_{GS} = 0 \text{ V}$			-1		
Zero Gate Voltage Drain Current	1DSS	$V_{DS} = -24 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55^{\circ}\text{C}$			-5	uA	
On-State Drain Current ^A	$I_{D(on)}$	$V_{DS} = -5 \text{ V}, V_{GS} = -10 \text{ V}$	-50			A	
		$V_{GS} = -10 \text{ V}, I_D = -9.5 \text{ A}$			19		
Drain-Source On-Resistance ^A	r _{DS(on)}	$V_{GS} = -4.5 \text{ V}, I_D = -7.5 \text{ A}$			30	mΩ	
	, ,	$V_{GS} = -10 \text{ V}, I_D = -9.5 \text{ A}, T_J = 55^{\circ}\text{C}$			29		
Forward Tranconductance ^A	g_{fs}	$V_{DS} = -15 \text{ V}, I_D = -9.5 \text{ A}$		31		S	
Diode Forward Voltage	V_{SD}	$I_S = -2.1 \text{ A}, V_{GS} = 0 \text{ V}$		-0.7		V	
Dynamic ^b	-						
Total Gate Charge	Q_{g}	$V_{DS} = -15 \text{ V}, V_{GS} = -4.5 \text{ V},$		15.3			
Gate-Source Charge Q_{gs}		$V_{DS} = -13 \text{ V}, V_{GS} = -4.3 \text{ V},$ $I_{D} = -9.5 \text{ A}$		5.2		nC	
Gate-Drain Charge	Q_{gd}	I _D = -9.5 A		5.8			
Switching							
Turn-On Delay Time	$t_{d(on)}$			15			
Rise Time	$t_{\rm r}$	$V_{DD} = -15 \text{ V}, R_L = 15 \Omega, I_D = -1 \text{ A}$		12		nS	
Turn-Off Delay Time	$t_{d(off)}$	$V_{GEN} = -10 \text{ V}, R_G = 6\Omega$		62			
Fall-Time	t_{f}			46			

Notes

- a. Pulse test: $PW \le 300us duty cycle \le 2\%$.
- b. Guaranteed by design, not subject to production testing.

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2

Typical Electrical Characteristics (P-Channel)

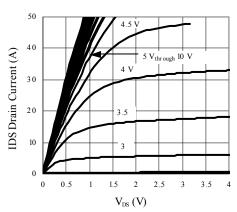
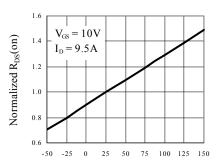


Figure 1. On-Region Characteristics



 $T_{\text{J}} \mbox{ Juncation Temperature ($^{\circ}\!C$)}$ Figure 3. On-Resistance Variation with Temperature

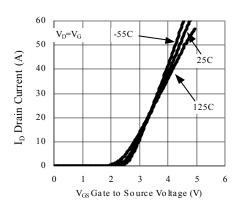


Figure 5. Transfer Characteristics

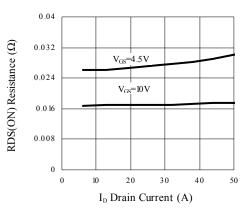


Figure 2. On-Resistance with Drain Current

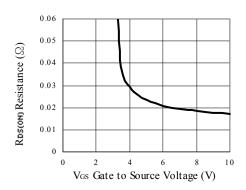


Figure 4. On-Resistance Variation with

Gate to Source Voltage

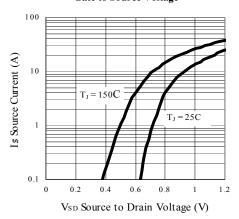
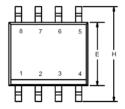


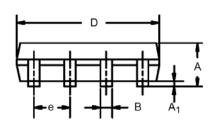
Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature

Typical Electrical Characteristics (P-Channel) 2000 $V_D = 10V$ Ciss I_D=-9.5A Vgs Gate to Source (V 1500 Capacitance (pF) 1000 Coss 500 Crss 0 20 25 30 5 20 Qg, Total Gate Charge (nC) $V_{DS}(V)$ Figure 7. Gate Charge Characteristics Figure 8. Capacitance Characteristics limited 45 40 35 I_D Current (A) 30 25 0mS 20 15 100mS 0.1 10 0.01 0.001 0.1 V_{DS} Drain to Source Voltage (V) TIME(S) Figure 9. Maximum Safe Operating Area Figure 10. Single Pulse Maximum Power Dissipation Normalized Thermal Transient Junction to Ambient 1. Duty Cycal D = t1/t20.01 2. Per Unit Base R_{θJA} =70C/W Single Pulse $3. T_{JM} - T_A = P_{DM} Z_{\theta jc}$ 4. Sureface Mounted 0.001 0.0001 0.001 0.01 0.1 10 100 1000 Square Wave Pulse Duration (S) Figure 11. Transient Thermal Response Curve

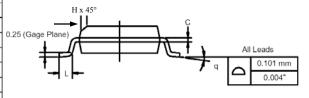
Package Information

SO-8: 8LEAD





	MILLIN	IETERS	INC	HES
Dim	Min	Max	Min	Max
Α	1.35	1.75	0.053	0.069
A ₁	0.10	0.20	0.004	0.008
В	0.35	0.51	0.014	0.020
С	0.19	0.25	0.0075	0.010
D	4.80	5.00	0.189	0.196
E	3.80	4.00	0.150	0.157
е	1.27	BSC	0.050	BSC
Н	5.80	6.20	0.228	0.244
h	0.25	0.50	0.010	0.020
L	0.50	0.93	0.020	0.037
q	0°	8°	0°	8°



5

Ordering information

• AM4835P-T1-XX

- A: Analog Power

- M: MOSFET

– 4835: Part number

– P: P-Channel

- T1: Tape & reel

– XX: Blank: Standard

PF: Leadfree